

application.

According to the examiner's opinion, please refer to 762, patent, which includes a plurality of upper metal sheets stacked on the lower metal sheets.

Therefore, 762, patent does not disclosed a similar structure to that of this
5 application, and does not motivate the applicant to finish this application.

In light of the above amendments and argument, Applicant now asserts that all of the grounds for rejection have been traversed or overcome by amendments, and that all of the present claims are in condition for immediate allowance. Applicant therefore requests reconsideration of the objections and
10 rejections, and solicits allowance of the present claims at an early date.

Thank you for your consideration.

Respectfully submitted,

Date: 8, 26, 2004

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 5 and 6 have been canceled.

- 5 1. A substrate structure for an integrated circuit package to be electrically connected to a printed circuit board, the substrate structure comprising:
- a plurality of lower metal sheets arranged in an array, each of the lower metal sheets having an upper surface and a lower surface;
- a plurality of upper metal sheets arranged in an array, each of the upper
- 10 metal sheets having an upper surface and a lower surface, the lower surfaces of the upper metal sheets being stacked on the upper surfaces of the lower metal sheets; and
- an encapsulant for encapsulating the lower metal sheets and the upper metal sheets, wherein the upper surfaces of the upper metal sheets are exposed from the
- 15 encapsulant, and the lower surfaces of the lower metal sheets are exposed from the encapsulant and electrically connected to the printed circuit board.
2. The substrate structure according to claim 1, further comprising a middle board arranged among and flush with the upper metal sheets, and the integrated circuit package being mounted to the middle board.
- 20 3. The substrate structure according to claim 1, wherein the encapsulant is made of plastic material.
- (5. The method according to claim 1, further comprising:

arranging a middle board among and flush with the upper metal sheets, and the integrated circuit package being mounted to the middle board.]

[6. The method according to claim 1, wherein the encapsulant is made of industrial plastic material by way of injection molding.]